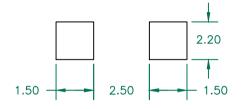
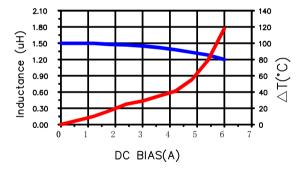
## MGV04021R5M-10

## PHYSICAL DIMENSIONS:

Α	4.50	±	0.50
В	4.10	$\pm$	0.30
С	2.00	±	0.30
D	1.50	±	0.30
Ε	1.00	±	0.50

## LAND PATTERNS FOR REFLOW SOLDERING

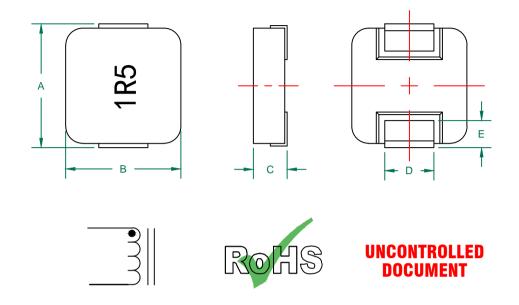




## ELECTRICAL SPECIFICATION @ 25°C

	Min	Nom	Max
INDUCTANCE (uH) L @ 100 KHz/0.25V ± 20%	1.20	1.50	1.80
DCR $(\Omega)$			0.046

Sati	uration Current <sup>3</sup> Isat (A)	6.00
Tem Curr	perature Rise ent Irms <sup>4</sup> (A)	4.00



NOTES: UNLESS OTHERWISE SPECIFIED

- 1.COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2.OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
- 3.SATURATION CURRENT Isat IS DEFINED AS MAXIMUM AMOUNT OF CURRENT BY WHICH INDUCTANCE WILL DROP BY TYPICAL VALUE OF 30% OF INITIAL INDUCTANCE (Ta=25±5°C).
- 4.TEMPERATURE RISE CURRENT (Irms): DC CURRENT THAT CAUSES THE TEMPERATURE RISE (  $\Delta T \leq 40^{\circ}$ C) FROM 25°C AMBIENT.

		DIMENSIONS ARE IN mm. This print is the property of Laird							
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ı					reserved.				
ı					PROJECT/PART NUMBER:	REV	PART TY	PE:	DRAWN BY:
ł					MGV04021R5M-10	В		WER CTOR	QIU
ı	В	UPDATE LOGO	04/21/15	QIU	DATE: 02/19/13	ALE:	ITS	SHEET:	
ı	Α	ORIGINAL DRAFT	02/19/13	QIU		OOL #	113		
Ì	REV	DESCRIPTION	DATE	INT		NL #	-	1	of 1